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ABSTRACT

An electronic component comprises a heat source component provided on a substrate; a case component covering the heat source component; a heat receiving component facing the case component; and a wall portion protruding from the heat receiving component, the wall portion configured to transfer heat indirectly transferred from the heat source component to the heat receiving component, wherein a heat release path of heat indirectly transferred from the heat source component to the wall portion includes a path away from the heat receiving component, the path extending in a wall portion direction toward the wall portion in a direction along a front surface of the heat receiving component.

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